

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl

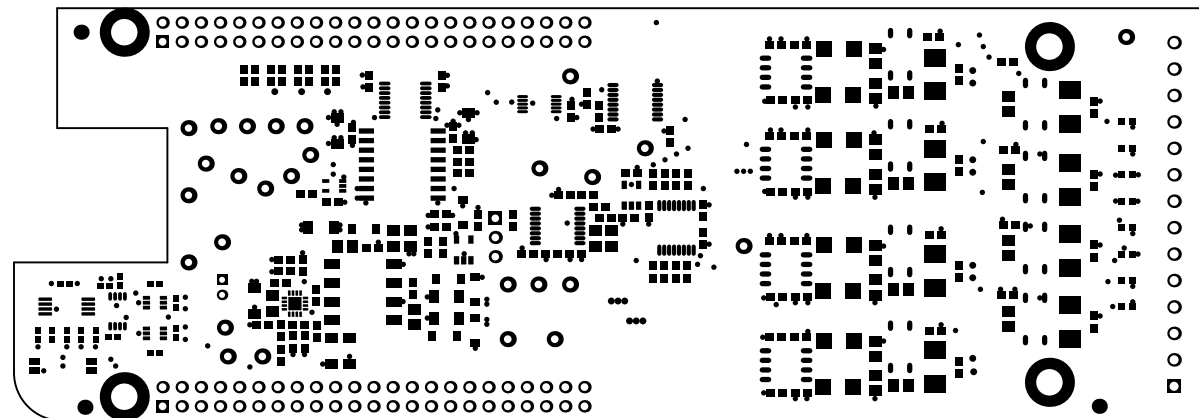
LAYER NAME = Top Overlay

TID #: TIDA-01333

PLOT NAME = Top Overlay

GENERATED : 23.02.2017 08:50:59

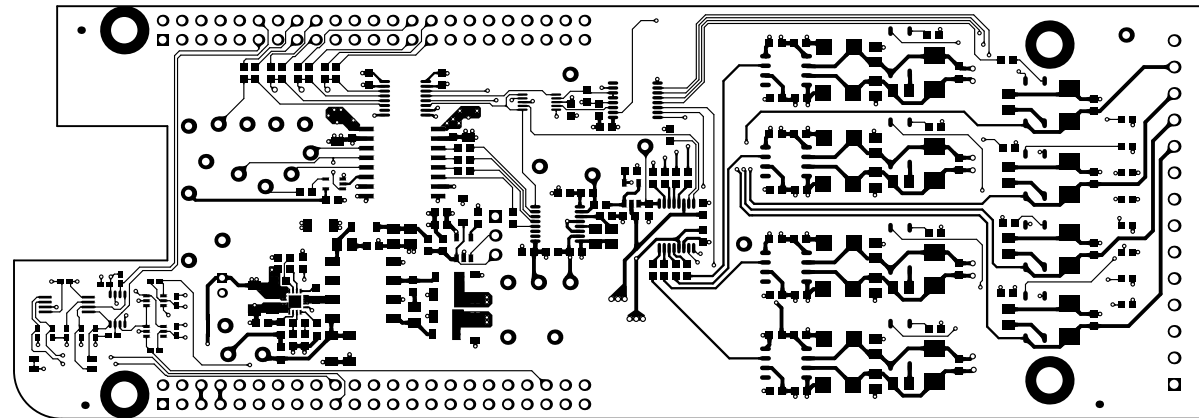
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Top Solder
PLOT NAME = Top Solder Mask

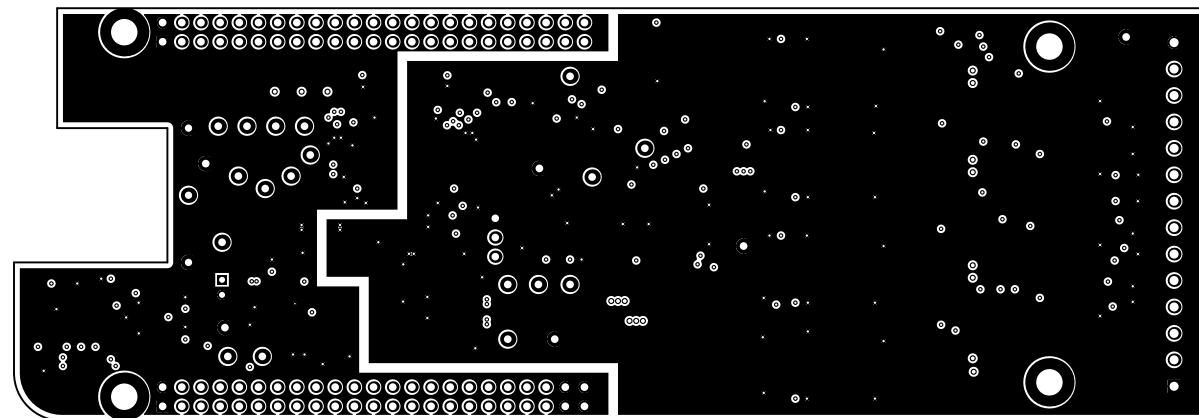
BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:00 TEXAS INSTRUMENTS

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				///
2	Top Solder	Solder Resist	0,40mil	3,5	///
3	Top Layer	Copper	1,40mil		///
4	Dielectric 1		8,00mil	4,2	///
5	GND	Copper	1,40mil		///
6	Dielectric 2	FR-4	40,00mil	4,2	///
7	VDD	Copper	1,40mil		///
8	Dielectric 3		8,00mil	4,2	///
9	Bottom Layer	Copper	1,40mil		///
10	Bottom Solder	Solder Resist	0,40mil	3,5	///
11	Bottom Overlay				///



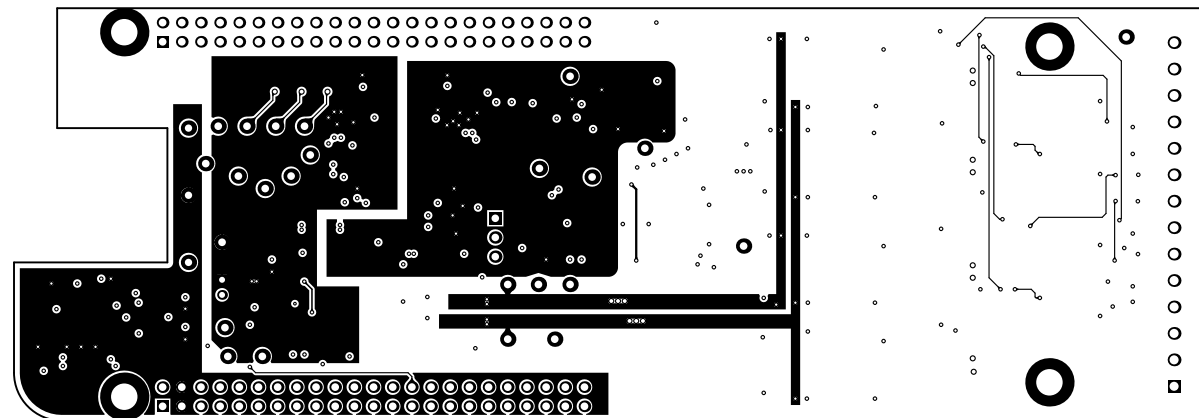
ALL ARTWORK VIEWED FROM TOP SIDE
 LAYER NAME = Top Layer
 PLOT NAME = Top Layer

BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
 TID #: TIDA-01333
 GENERATED : 23.02.2017 08:51:01 TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME =
PLOT NAME = Signal Layer 1

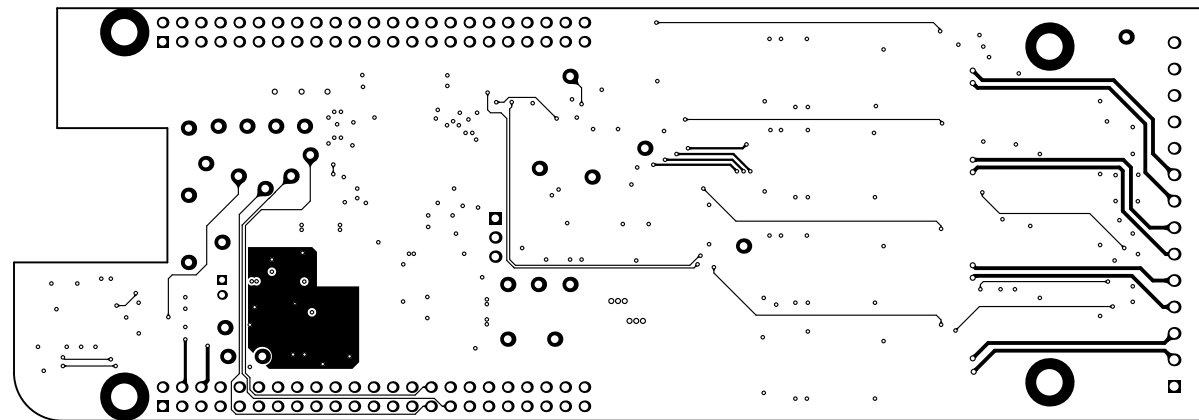
BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:02 TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME =
PLOT NAME = Signal Layer 2

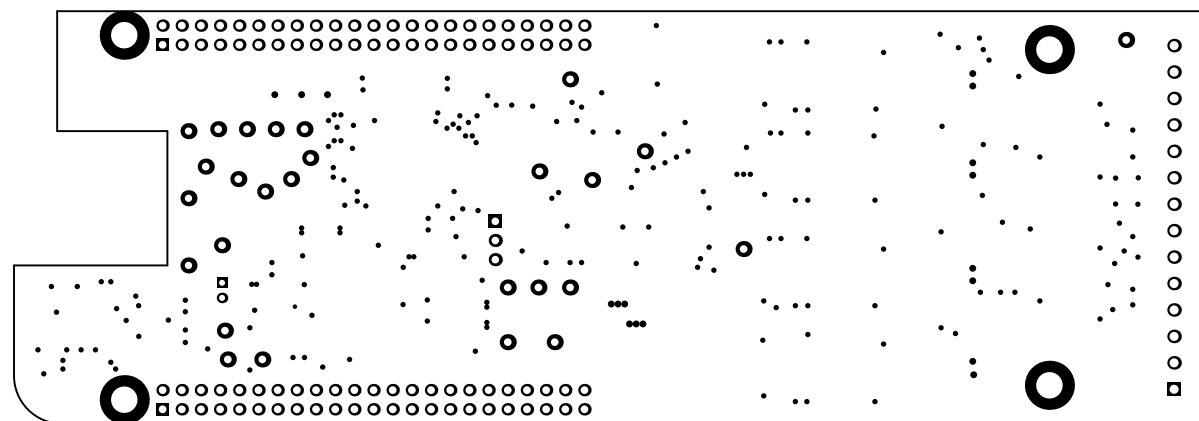
BOARD #: TIDA-01333 REV: E1
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:03

SUN REV: Not In VersionControl
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom Layer
PLOT NAME = Bottom Layer

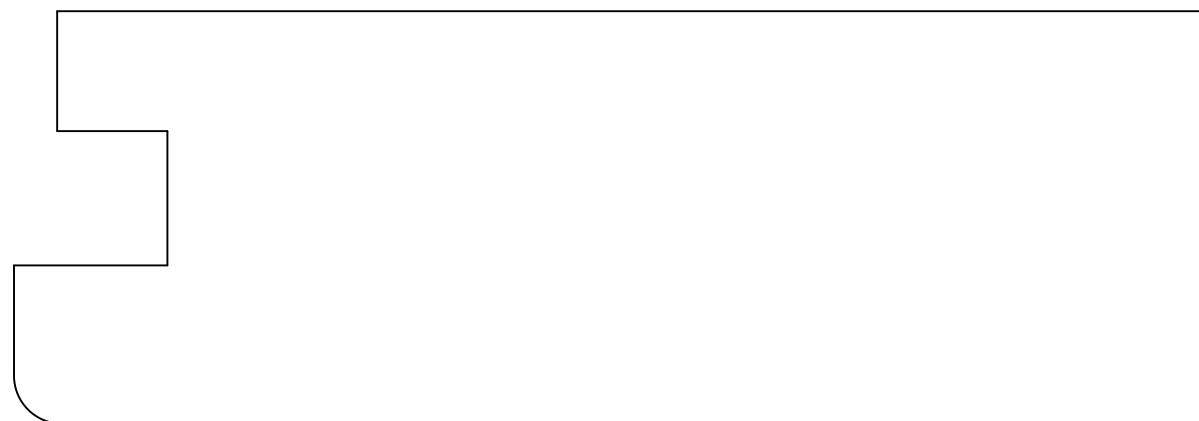
BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:04 TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom Solder
PLOT NAME = Bottom Solder Mask

BOARD #: TIDA-01333 REV: E1
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:05

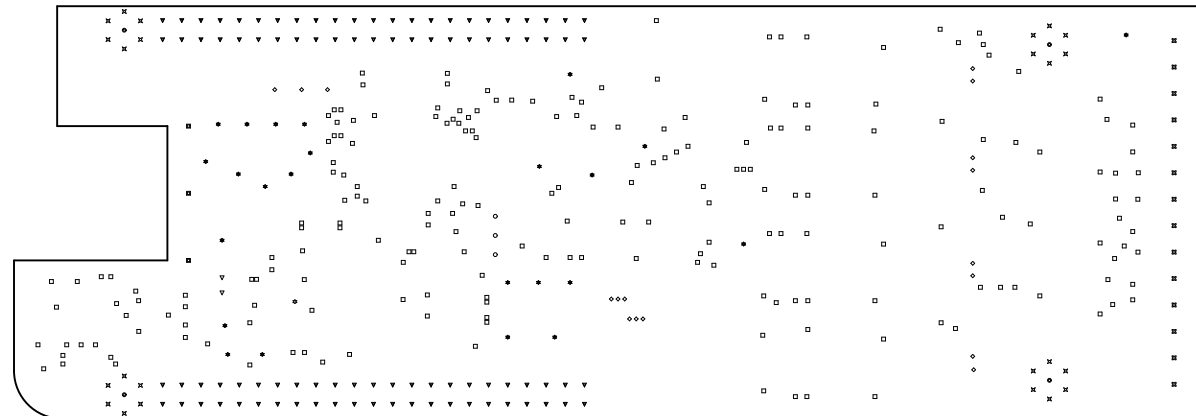
SUN REV: Not In VersionControl
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = Bottom Overlay
PLOT NAME = Bottom Overlay

BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-01333
GENERATED : 23.02.2017 08:51:06 TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✱	1	7,87mil (0,200mm)	PTH	Round
□	210	12,00mil (0,305mm)	PTH	Round
✱	24	19,69mil (0,500mm)	PTH	Round
◇	17	20,00mil (0,508mm)	PTH	Round
▽	2	31,00mil (0,787mm)	PTH	Round
■	3	37,99mil (0,965mm)	PTH	Round
○	3	39,37mil (1,000mm)	PTH	Round
✱	24	40,00mil (1,016mm)	PTH	Round
▽	92	40,16mil (1,020mm)	PTH	Round
✱	14	47,24mil (1,200mm)	PTH	Round
●	4	137,80mil (3,500mm)	PTH	Round
	394 Total			



ALL ARTWORK VIEWED FROM TOP SIDE
 LAYER NAME = Drill Drawing
 PLOT NAME = Drill Drawing

BOARD #: TIDA-01333 REV: E1
 TID #: TIDA-01333
 GENERATED : 23.02.2017 08:51:07

SUN REV: Not In VersionControl
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ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = M2 Board Dimensions
PLOT NAME = Board Dimensions

BOARD #: TIDA-01333 REV: E1 SUN REV: Not In VersionControl
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